Daniel Sher

y @overleaf_example

in example



Education

2024 – present Be.Eng. Electronic Engineering, Engineering Department, HKU, Hong Kong China. GPA: 3.92

Department, HKU, Hong Kong China.

GPA: 3.92.

HDEng Electronic and information engineering, Engineering Department, HKU, Hong Kong China.

2014 – 2020 High school YMCA of Hong Kong Christian college, Hong Kong, China.

Work Experience

Volunteer Experience

2022 – 2023 Volunteer Peer Supporters for Students with Special Educational Needs, CEDARS, HKU.

Intern Experience

2021 – 2023 Intern Software Engineer Internship, xx Co Ltd, Suzhou, Jiangsu, China.

Employment Experience

2014 – · · · Community Witch, Village of Frying Pans.

2022 – 2023 Lecturer. Information Technology Department, School of Engineering, Science and Technology, XYZ College.

Research Publications

• xxx, xxx, Nature, 2023.

Activity

Social Club

2022 – 2023 Running Club Peer Supporters for Students with Special Educational Needs, CEDARS, HKU.

Leadership

2021 – 2023 **Hall Student Mentor** xx House, HKU.

Skills

Languages Strong reading, writing and speaking competencies for English, Mandarin Chinese, Bahasa Malaysia.

Coding | Java, PHP, Python, R, sql, хмl/хsl, Lage, ...

Databases Mysql, Postgresql, Hsql, sqlite, LotusNotes.

Web Dev HTML, css, JavaScript, Apache Web Server, Tomcat Web Server.

Misc. Academic research, teaching, training, consultation, LTEX typesetting and publishing.

Awards and Prizes

Awards and Achievements

2002 Merit Award, Random Training Course held at Secret Location.

Department Prize for Outstanding Student Performance, Unseen University.

Certification

2014 Certified XYZ Practioner. Awarded by X Insitute.

2006 Certified Level 3 in ABC. Awarded by ABC.